

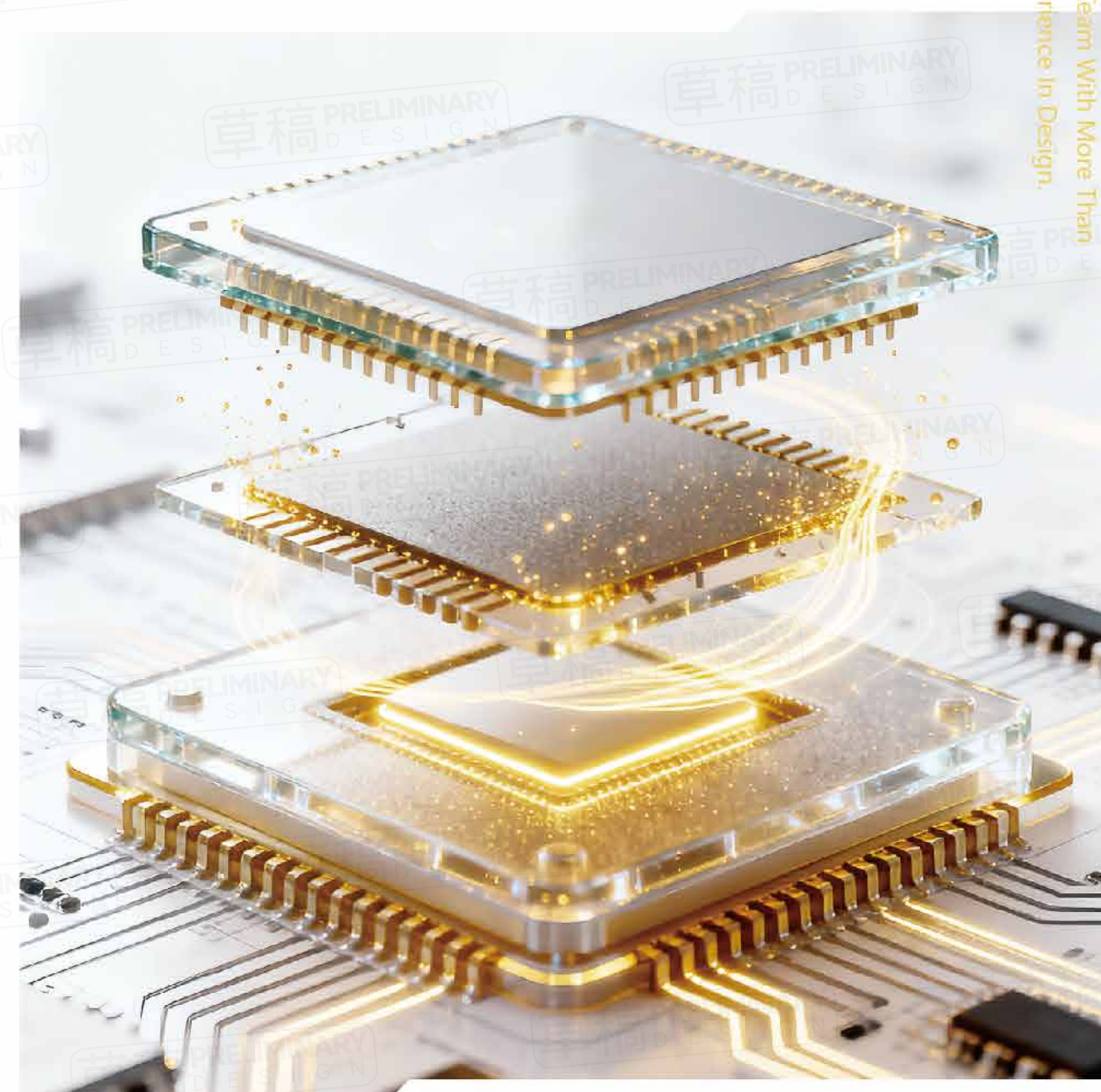
Act Responsible Think Sustainable



IC TESTING TOTAL SOLUTION PROVIDER

— 半导体芯片测试解决方案供应商

Professional Team With More Than
30 Years Experience In Design.



苏州富智微科技有限公司
Suzhou Fuzhi Micro Technology Co., Ltd.

中国·苏州工业园区
JG-Tech 中国区分公司

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Professional Team With More Than 30 Years Experience In Design.

FMTECH



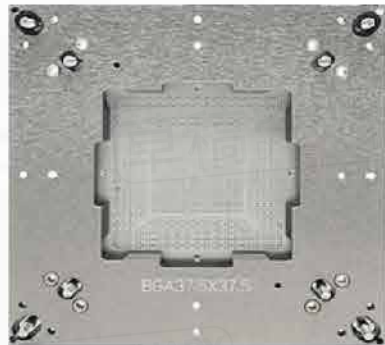
A Member of
JG TECH

- 半导体IC测试座及测试探针
- Handler/Tester 配套转换治具
- 测试探针清洁方案

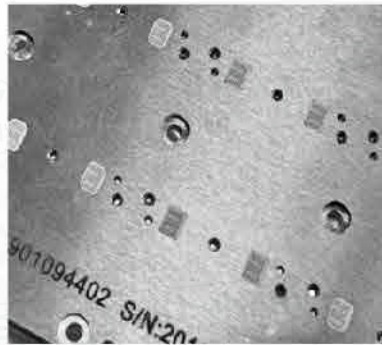
SOCKET

测试座

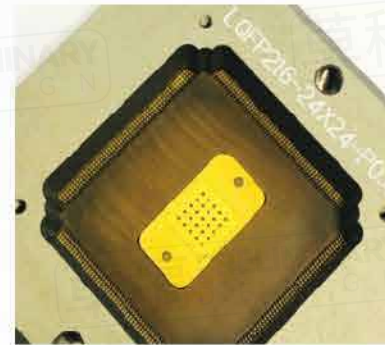
The socket can be designed according to the customer's IC packaging and electrical performance requirements. Currently, the minimum ball pitch it can match is 0.15 millimeters.



Coaxial Socket



WLCSP Socket



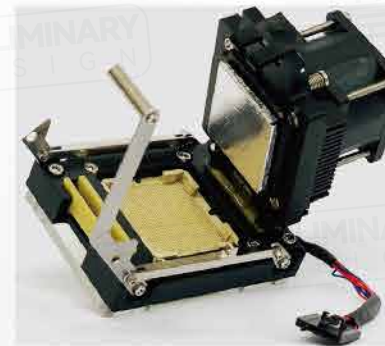
Rolling Socket



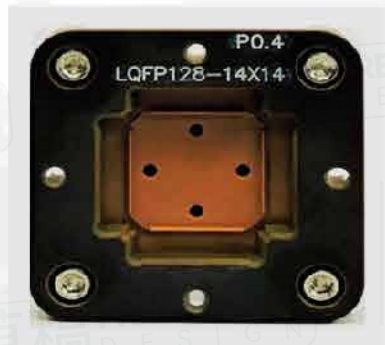
POP Socket



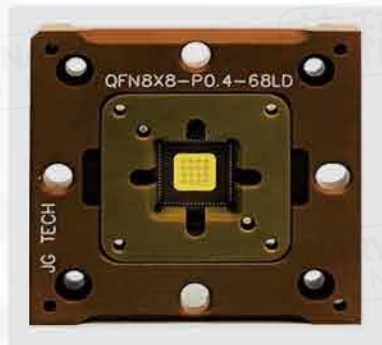
Rubber Socket



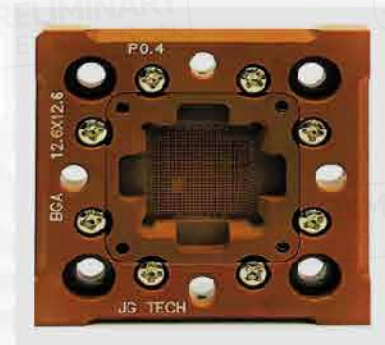
Burn in Socket



QFP Socket



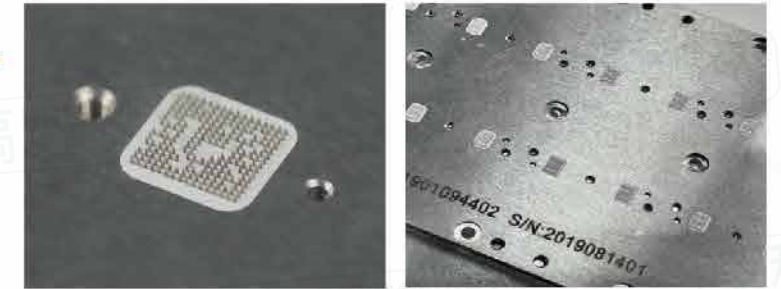
QFN Socket



BGA Socket

WLCSP SOCKET

WLCSP测试座



KEY FEATURES

Ideal for ultra high-speed, high-accuracy machining centers

Ideal for small holes for fine pitch

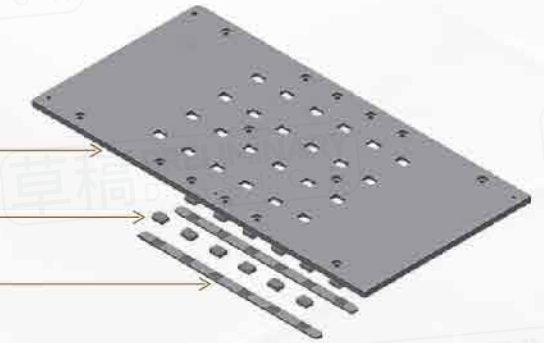
Workable drilling diameter = 0.05 mm

1、Material Setting Simulation Result

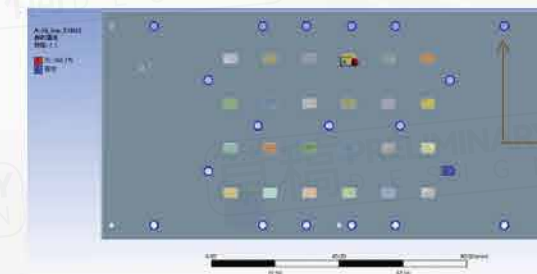
Frame – SUS303

Housing (Ceramic)

Retainer – SP1+



2、Fixed Position Setting

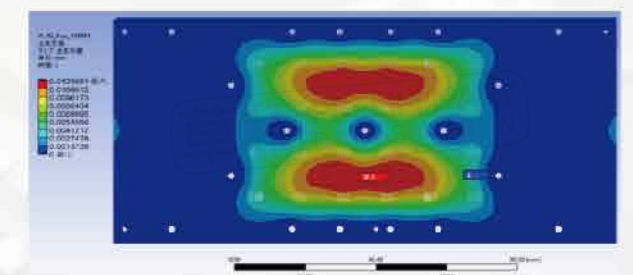


To set screw tightening location as a fixed position

3、Simulation Result

Deformation: 2.365μm

Deformation value 0.012mm within tolerance spec

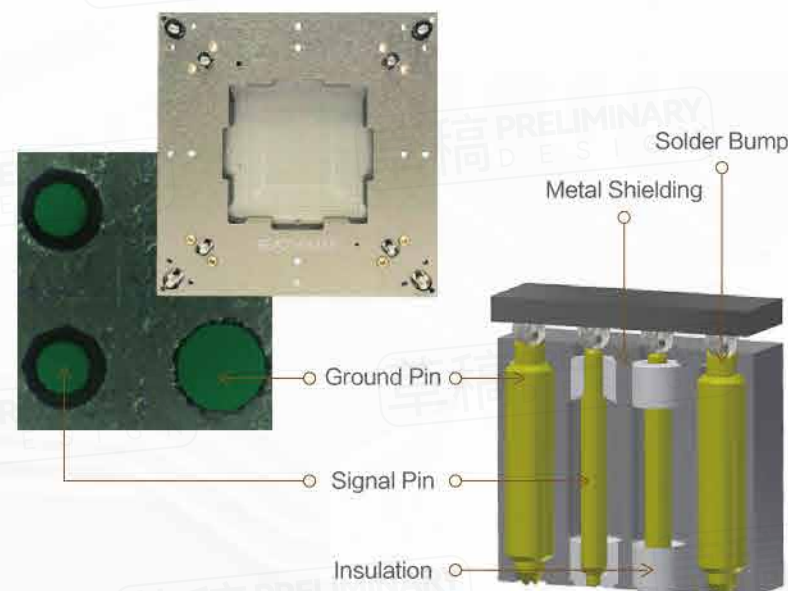


COAXIAL SOCKET

同轴测试座

KEY FEATURES

- High isolation full ground shielding from board to DUT
- Exceptional DC and RF performance
- High frequency
- Excellent thermal management
- High speed > 112Gbps



CONFIGURATIONS / INTERFACE OPTIONS

- Automated Test
- Handler specific design / configuration
- Singulated package
- Optional manual actuator
- Probe head for WLCSP

ENVIRONMENTAL

- Temperature Range:
-55°C to +155°C

MATERIALS

- Housing Material:
Aluminum

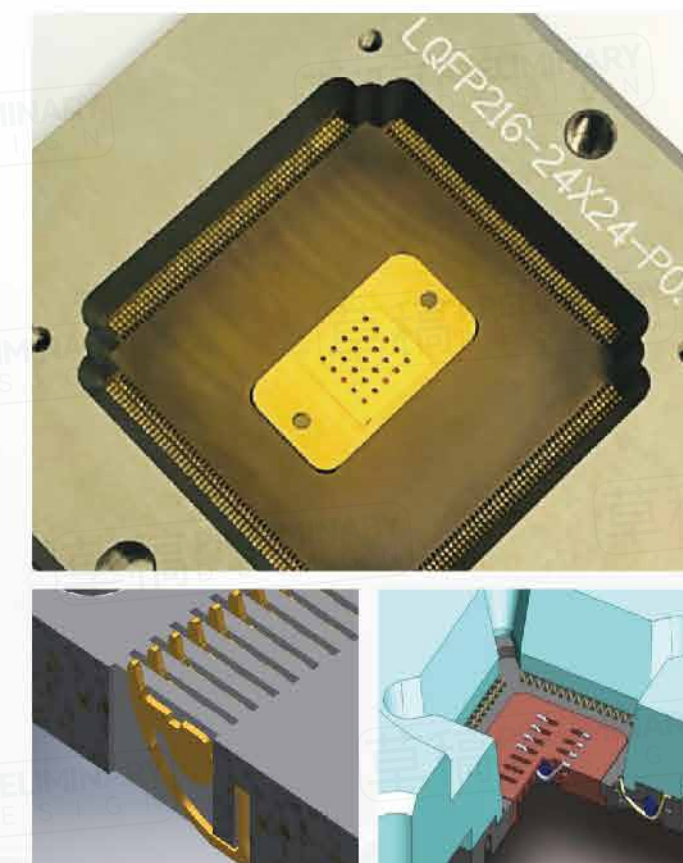
PACKAGES AND APPLICATIONS

- Packages: BGA, LGA
- Pitch: 0.4 mm, 0.5 mm, 0.8 mm or 1.0 mm

ROLLING SOCKET

Rolling测试座

The rolling socket can be applied to QFN and QFP package products. This product is characterized by its low contact resistance and short distance, all while exhibiting excellent RF performance. In addition to having a self-cleaning function, its probe also boasts a significantly longer lifespan and stability.



KEY FEATURES

- High Frequency up to 20GHz Particles drop automatically

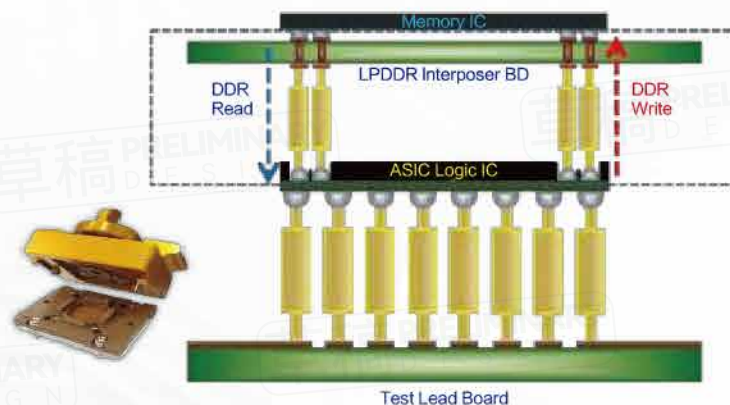
PKG	Size	Pin Count	Pitch
QFN	3x3~12x12	9~128	1.0~0.3mm
QFP	5x5~24x24	28~216	1.0~0.4mm

POP SOCKET

POP测试座

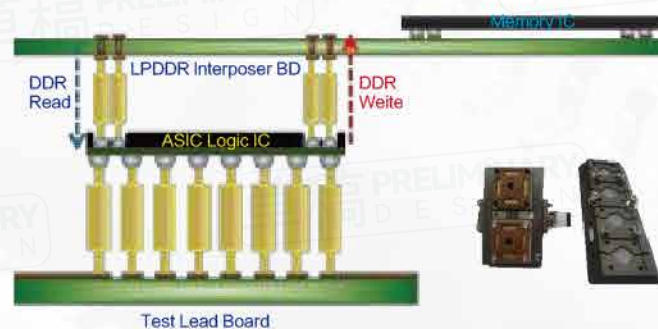
G3 PoP Socket

- * App. Standards: LPDDR6, up to 14400Mbps
- * Signal Paths: DDR pins, interposer(DDR shift)
- * Test configure: EVB manual, FT(ATE), SLT, SFT



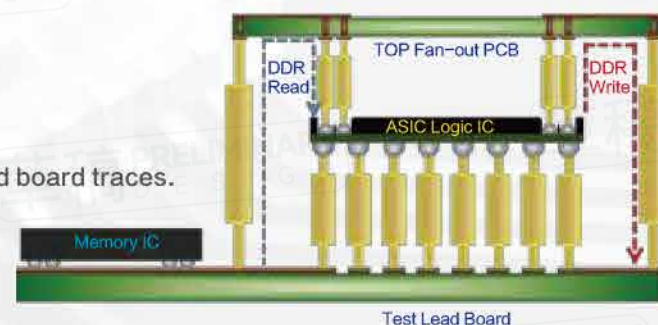
G2 PoP Socket

- * App. Standards: LPDDR2/3, up to 2133Mbps
- * Signal Paths: DDR pins, interposer(DDR shift)
- * Test configure: EVB manual, FT(ATE), SLT



G1 PoP Socket

- * App. Standards: LPDDR2/3, up to 1600Mbps
- * Signal Paths: DDR pins, interposer, long pins, Load board traces.
- * Test configure: EVB manual, FT(ATE), SLT



BURN-IN SOCKET

崩应测试座

In the testing industry, IC lifespan is largely dependent on temperature. The burn-in socket can increase the reliability of IC tests in high- and low-temperature environments. The temperature specifications of our products range is from 150°C to -60°C.

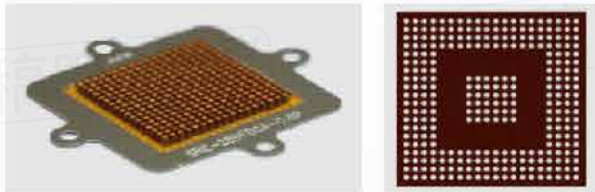


ITEM	SPEC
Working Temperature	-60°C ~ +150°C
Heater Spec	48V/50W
Device Watt	350W
Pogo Pin Current	3A

PCR

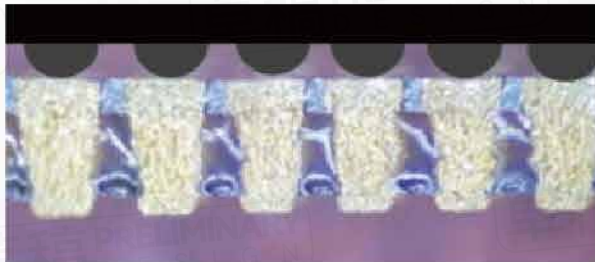
导电胶

S-TYPE (For Solder Ball Type)

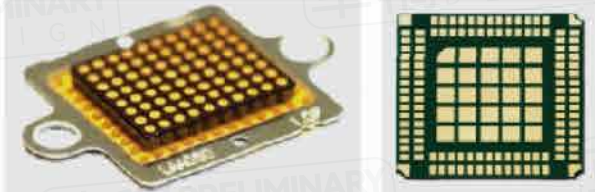


Contact Pad

BGA



N-TYPE (For No-Ball Type)



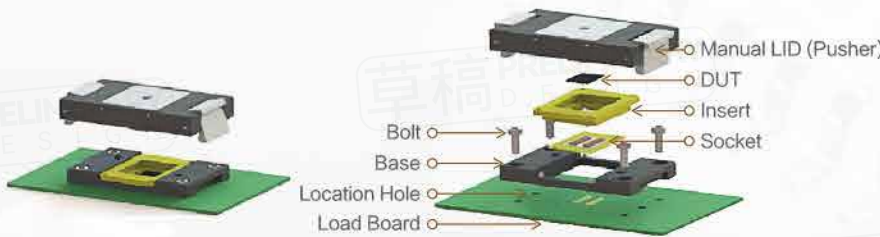
Contact Pad

LGA



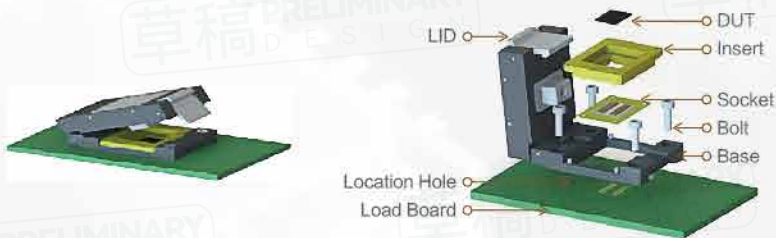
Open-Top Housing

* Used under Auto Test



Clamshell Housing

* Used under Manual Test, need separate board



Handle Type Housing

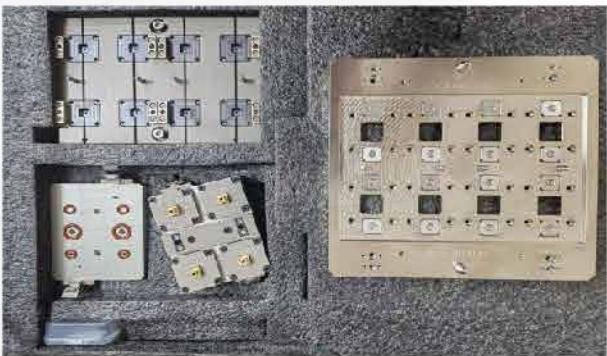
* Used under Manual Test, with many ball counts



Pin Spec	Pitch	0.25~1.00P
	Contact Length (Free)	0.35~0.90mm
	Contact Length (Pressed)	0.25~0.65mm
Frame	Pin Material	Gold Plated Metal Ball
	Frame Type	Molded or Bonded
Mechanical	Frame Material	FR4 or SUS
	Contact Force (gram/pin)	10~30
	Stroke (Compliance)	0.10~0.25mm
Electrical	Coplanarity	<50u m
	RF Bandwidth (-1dB @)	100~40GHz
	Resistance	<100mΩ
	Continuous Current /Pin	1~3A
	Inductance (nH)	Below 0.15
	Insulation Resistance	Over 100MΩ
Cleaning Frequency (Tape or Tool)		Every 20k insertions
Contactor Life Cycle		50K ~ 300K
Operating Temperature		-50° C to 155° C

CHANGE KIT

转换治具



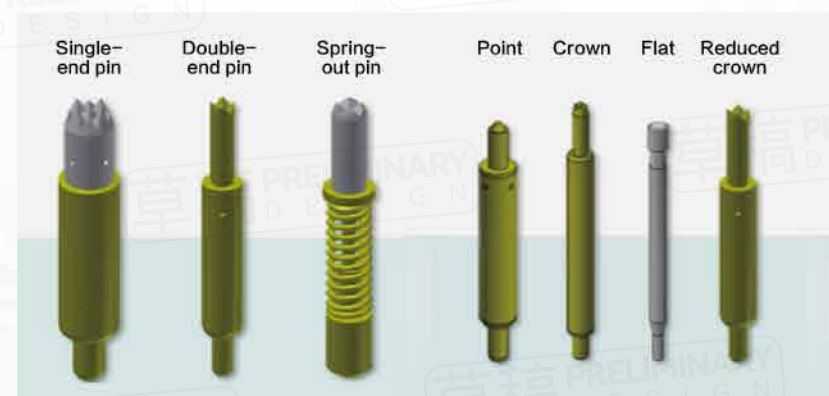
常高温Kit



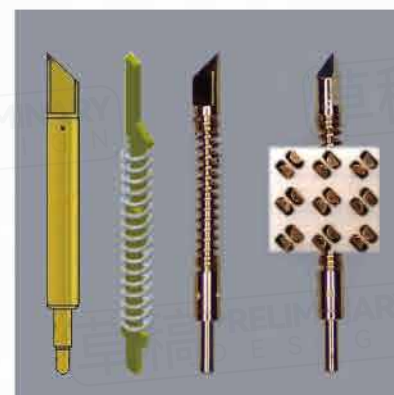
Tri-Temp / 高低温 Kit

TEST PROBE

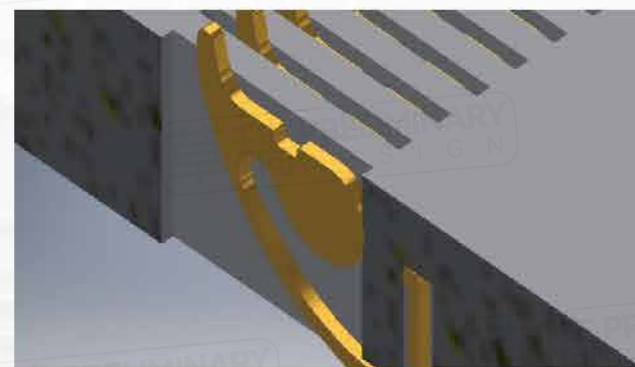
测试探针



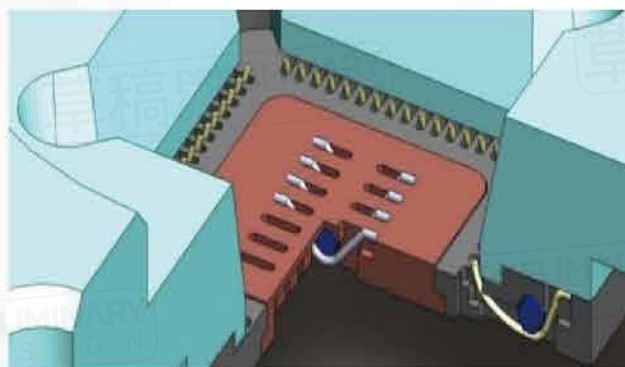
Pogo Pin



Kelvin Pin



Rolling Pin



PROBE CLEANING

探针清洁方案



Nano Steel Brush / 纳米钢刷



Clean Pad / 清洁片



Laser Cleaner / 镭射清洁机

LASER CLEANER

镭射清洁机

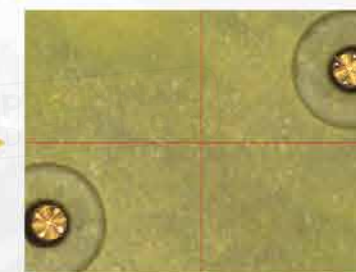
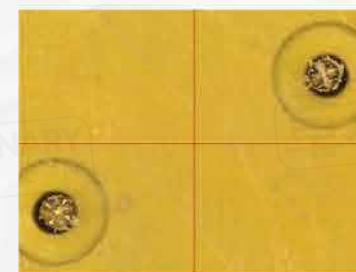
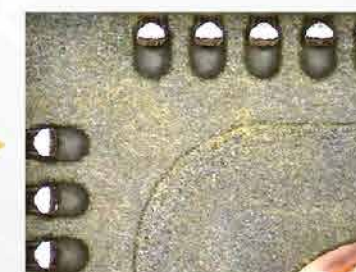
THE PHYSICS OF LASER CLEANING

Use material of laser light absorption, high absorption rate of the material, such as carbon, dust, in a short period of time to absorb more laser energy, temperature rising moment and do not turn the heat off, and the material are vaporized.



Before

After



The automated equip can support cleaning of 4 sites together.

